RoHS Declaration

Directive 2011/65/EU as amended by (EU) 2015/863 · SRT-Microcéramique products

Scope	Multilayer ceramic capacitors, stacked capacitors, filters and related components manufactured by SRT-Microcéramique
Date of issue	25/11/2026
Revision	A

DECLARATION

The RoHS status of an SRT-Microcéramique part number depends on its termination finish, identified by its code in the part number. Part numbers with a lead-free termination finish comply with Directive 2011/65/EU (RoHS) as amended by Commission Delegated Directive (EU) 2015/863: none of the restricted substances listed below is present above its maximum concentration value, by weight in homogeneous materials.

Part numbers with a tin-lead (SnPb) termination finish contain more than 0.1 % lead by weight in a homogeneous material. They are therefore **not compliant** with Directive 2011/65/EU as amended by (EU) 2015/863. SnPb finishes are supplied for tin-whisker mitigation in high-reliability equipment, in particular equipment outside the scope of the directive (Article 2(4): military equipment, equipment designed to be sent into space). A lead-free alternative (e.g. NiSn finish, termination code X) is available on request.

ROHS STATUS BY TERMINATION FINISH

CODE	TERMINATION FINISH	ROHS STATUS
C	CuSn Non Magnetic	**COMPLIANT**
CP	CuSn Polymer Non Magnetic	**COMPLIANT**
CW	Gold Flash Non Magnetic	**COMPLIANT**
F	AgPdPt	**COMPLIANT**
G	Gold Thick	**COMPLIANT**
M	NiSn Microstrip	**COMPLIANT**
P	Polymer	**COMPLIANT**
Q	Silver	**COMPLIANT**
S	Dipped SAC305	**COMPLIANT**
W	Gold Flash	**COMPLIANT**
X	NiSn	**COMPLIANT**
H	Dipped SnPb	**NOT COMPLIANT — lead-bearing finish**
HP	Dipped SnPb Polymer	**NOT COMPLIANT — lead-bearing finish**
I	Plated SnPb	**NOT COMPLIANT — lead-bearing finish**
IP	Plated Polymer SnPb	**NOT COMPLIANT — lead-bearing finish**
N	Plated SnPb Lead Frame	**NOT COMPLIANT — lead-bearing finish**

RESTRICTED SUBSTANCES (ANNEX II)

SUBSTANCE	MAX. CONCENTRATION (HOMOGENEOUS MATERIAL)	STATUS — LEAD-FREE FINISHES
Lead (Pb)	0.1 %	Not intentionally added — below limit
Mercury (Hg)	0.1 %	Not intentionally added — below limit
Cadmium (Cd)	0.01 %	Not intentionally added — below limit
Hexavalent chromium (Cr VI)	0.1 %	Not intentionally added — below limit
Polybrominated biphenyls (PBB)	0.1 %	Not intentionally added — below limit
Polybrominated diphenyl ethers (PBDE)	0.1 %	Not intentionally added — below limit
Bis(2-ethylhexyl) phthalate (DEHP)	0.1 %	Not intentionally added — below limit
Butyl benzyl phthalate (BBP)	0.1 %	Not intentionally added — below limit
Dibutyl phthalate (DBP)	0.1 %	Not intentionally added — below limit
Diisobutyl phthalate (DIBP)	0.1 %	Not intentionally added — below limit

ADDITIONAL INFORMATION

- Lead-free terminations: suitable for lead-free reflow soldering according to IPC/JEDEC J-STD-020 and EN IEC 60068-2-58; solderability verified with SAC305 alloy (Sn96.5Ag3Cu0.5).
- SnPb terminations: intended for tin-lead soldering processes; do not use in RoHS-scope equipment.
- REACH (EC 1907/2006): see SRT-Microcéramique REACH declaration dated 25/11/2026 (SVHC candidate list).
- A RoHS certificate for a specific part number is available on request from commercial@srt-mc.com.
- This declaration applies to products delivered from its issue date; it reflects the legislation in force at that date.

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